

AMP | AMP Twin-Leaf

TE Internal #: 583859-5

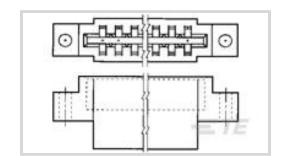
Housing, Receptacle, Wire-to-Board, 18 Position, 3.96 mm [.156 in] Centerline, Crimp, 2 Row, Black, Printed Circuit Board, AMP Twin-

Leaf

View on TE.com >



Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Assemblies & Housings



Connector Product Type: Housing

Connector & Housing Type: Receptacle

Connector System: Wire-to-Board

Number of Positions: 18

Centerline (Pitch): 3.96 mm [.156 in]

Features

Product Type Features

Connector Product Type	Housing	
Connector & Housing Type	Receptacle	
Connector System	Wire-to-Board	
Connector & Contact Terminates To	Printed Circuit Board	
Configuration Features		
Number of Dual Positions	18	

Number of Positions	18
NI. was la au af Danna	2

Number of Rows 2

Contact Features

Contact Current Rating (Max)	5 A	
------------------------------	-----	--

Termination Features

Termination Method to Wire & Cable	Crimp
------------------------------------	-------

Mechanical Attachment

Strain Relief	Without
PCB Mount Retention	Without
Panel Mount Feature Type	Mounting Ears
Connector Mounting Type	Board Mount

Housing Features



Housing Material	Polyester GF	
Centerline (Pitch)	3.96 mm[.156 in]	
Housing Color	Black	
Dimensions		
	.75 in	
Usage Conditions		
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]	
Operation/Application		
Circuit Application	Power & Signal	
Industry Standards		
Glow Wire Rating	Standard Part - Not Glow Wire	
UL Flammability Rating	UL 94V-0	
Packaging Features		
Packaging Quantity	200	

Product Compliance

Packaging Method

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

Carton

Product Compliance Disclaimer

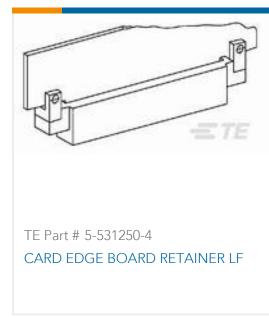
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

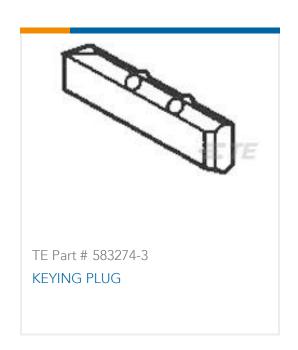


will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts







Also in the Series | AMP Twin-Leaf







Wire-to-Board Connector Assemblies & Housings(27)

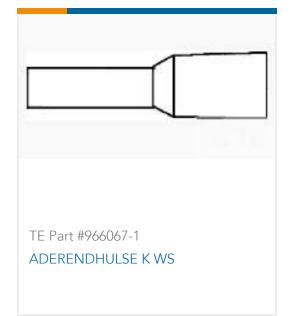


Wire-to-Board Connector Contacts(15)

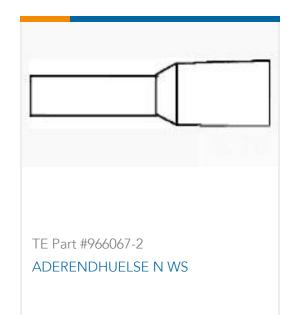
Customers Also Bought





















Documents

Product Drawings

TW-LF CRP HSG 18 POS

English

Product Specifications

Product Specification

English

Product Specification

English

Instruction Sheets

Instruction Sheet (U.S.)

English

Agency Approvals

UL Report

English